

Integrated Device Technology, Inc. 2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)							
PCN #: SR-0203-02 DATE: March 15, 2002 Product Affected: IDT7164 and IDT6116 Family		MEANS OF DISTINGUISHING CHANGED DEVICES: ☐ Product Mark ☐ Back Mark ☐ Date Code Top mark will have "4" following the					
Date Effective: June 15, 2002		☐ Other	=	to page 1 of attachment			
Contact: George Snell		l		1. F. 6			
Title: Quality Assurance Manager Phone #: (831) 754-4556		Attachment:	Yes	☐ No			
Fax #: (831) 754-4672 E-mail: george.snell@idt.com		Samples:	Available upon	request			
DESCRIPTION AND PURPOSE OF CHANGE: □ Die Technology							
Wafer Fabrication Process Assembly Process Equipment Material Manufacturing Site Data Sheet Other To consolidate Wafer Fab production from Salinas, California (Fab 2) to Hillsboro, Oregon (Fab 4). These qualified products will be transferred to IDT's Wafer Fab facility in Hillsboro, Oregon. These devices will be upgraded from Cmos 7 to Cmos 8 . Cmos 8 is an existing qualified proc at Fab 4.							
RELIABILITY/QUALIFICATION SUMMARY Qualification testing will verify that there is no chan request.		uct reliability. Qual	ification details are	available upon			
CUSTOMER ACKNOWLEDGMENT OF RECI IDT records indicate that you require written notific to grant approval or request additional information. it will be assumed that this change is acceptable. IDT reserves the right to ship either version manufa on the earlier version has been depleted.	eation of this cl If IDT does no	ot receive acknowle	edgement within 30	days of this notice			
Customer:		Approval fo	r shipments prio	r to effective date.			
Name/Date:	E-1	Mail Address:					
Title:	Pho	one#/Fax#:					
CUSTOMER COMMENTS:							
IDT ACKNOWLEDGMENT OF RECEIPT:							
RECD. BY:		DATE:					

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PCN Type: Fab Site Change

Data Sheet Change None Expected

Detail of Change

Transfer existing qualified products from Salinas, California Wafer Fab Facility (Fab 2) to Hillsboro, Oregon Wafer Fab Facility (Fab 4).

	Current Wafer Fab			Transfer Wafer Fab				
	Manufacturing	Technology	Wafer	Die	Manufacturing	Technology	Wafer	Die
Part Name	Site		Size	Revision	Site		Size	Revision
7164L	Salinas, CA	Cmos 7	6 inch	L	Hillsboro, OR	Cmos 8	8 inch	L4
6116L	Salinas, CA	Cmos 7	6 inch	L	Hillsboro, OR	Cmos 8	8 inch	L4

Conversion schedule (Estimated)

Base Device Production Shipments and Sample Availability

7164L4 June 15, 2002 6116L4 June 15, 2002 2975 Stender Way, Santa Clara, CA - 95054

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Qualification Plan: QS-0202-04

Expected Completion Date

6/1/2002 **Test Vehicle**

TOST VEHICLE		
	Plan	Actual Results
7164L	Sample / Accept	LOT #1
Operating Life Test: Dynamic @+135°C, Vcc=4V for 750 hours	116/0	
High Temp. Storage Life Test (Unbiased, 1000 hours @+150°C)	77 / 0	
Bake & Ballshear Test @ 200°C / 4 ball bonds per device	5/0	
Temperature Cycling: (-65°C to +150°C, 500 cycles)	45 / 0	
HAST: (Biased, 100 Hrs. @+130°C, +85%RH, 3 Atm.)	45 / 0	
Autoclave:(Unbiased, 2 Atm Saturated Steam, +121°C, 168 Hrs)	45 / 0	
ESD Human Body Model	9/0	
ESD Charged Device Model	6/0	
Latch up: (Tested to 1.5X Vcc)	10/0	

Product release is based on qualification of initial lot.

Characterization Data: Characterization will be completed as part of product qualification

and data available upon request. Characterization will verify

that there is no change to existing data sheet parameters.

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	Current	New Die			Bus		
Base Part Number	Die Rev	Rev	Interface	Vcc	Width	Depth	Density
IDT6116 Devices:							
IDT6116LA	L	L4	Asynch	5V	x8	2K	16K
IDT6116SA	L	L4	Asynch	5V	x8	2K	16K
		•					
IDT7164 Devices:							
IDT7164L	L	L4	Asynch	5V	x8	8K	64K
IDT7164S	L	L4	Asynch	5V	x8	8K	64K